

Specification Features:

- Fast Switching Device ($T_{RR} < 4.0$ nS)
- General Purpose Diodes
- RoHS Compliant
- Green EMC
- Matte Tin(Sn) Lead Finish
- Band Indicates Cathode
- Weight: approx. 0.01g



SOD-123F

DEVICE MARKING CODE:

Device Type	Device Marking
BAS16H	D1

Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
P_D	Power Dissipation	400	mW
T_{STG}	Storage Temperature Range	-65 to +150	$^\circ\text{C}$
T_J	Operating Junction Temperature	+150	$^\circ\text{C}$
V_{RSM}	Non-Repetitive Peak Reverse Voltage	100	V
V_{RRM}	Repetitive Peak Reverse Voltage	75	V
I_{FRM}	Repetitive Peak Forward Current	300	mA
I_O	Continuous Forward Current	150	mA
I_{FSM}	Peak Forward Surge Current (Pulse Width=1us)	2	A

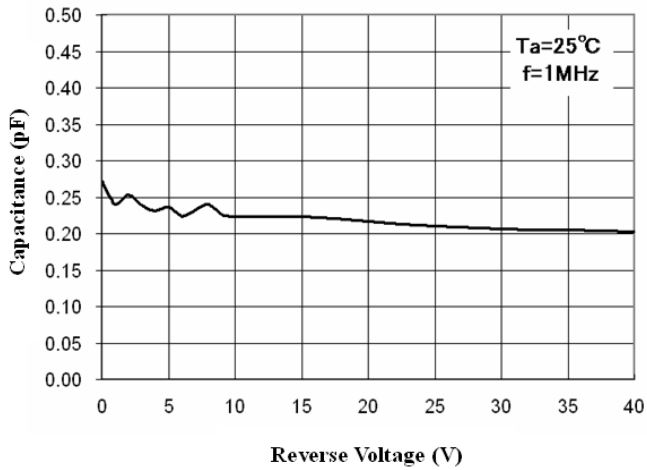
These ratings are limiting values above which the serviceability of the diode may be impaired.

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

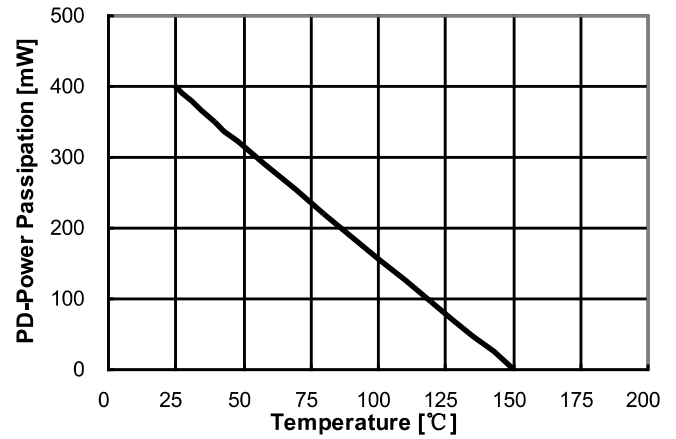
Symbol	Parameter	Test Condition	Limits		Unit
			Min	Max	
B_V	Breakdown Voltage	$I_R = 100\mu\text{A}$ $I_R = 5\mu\text{A}$	100 75		Volts
I_R	Reverse Leakage Current	$V_R = 20\text{V}$ $V_R = 75\text{V}$		25 5	nA μA
V_F	Forward Voltage	$I_F = 10\text{mA}$		1.0	Volts
T_{RR}	Reverse Recovery Time	$I_F = 10\text{mA}$ $I_R = 60\text{mA}$ $R_L = 100\Omega$ $I_{RR} = 1\text{mA}$		4	nS
C	Capacitance	$V_R = 0\text{V}$, $f = 1\text{MHz}$		4	pF

Typical Performance Characteristics

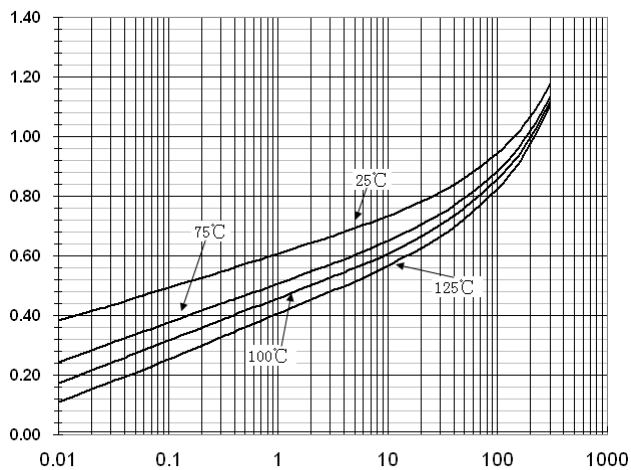
Total Capacitance



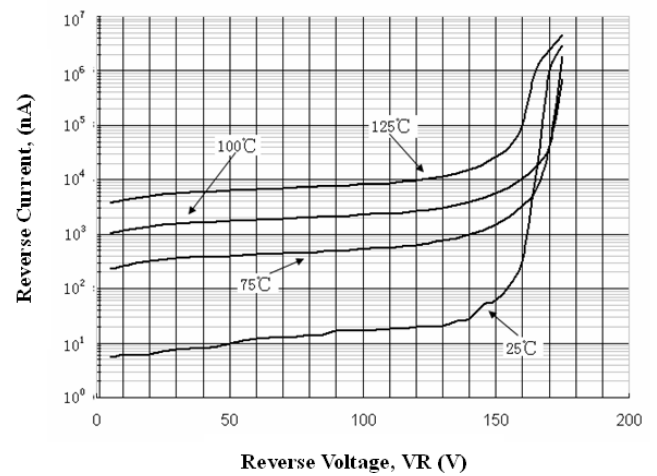
Power Derating Curve



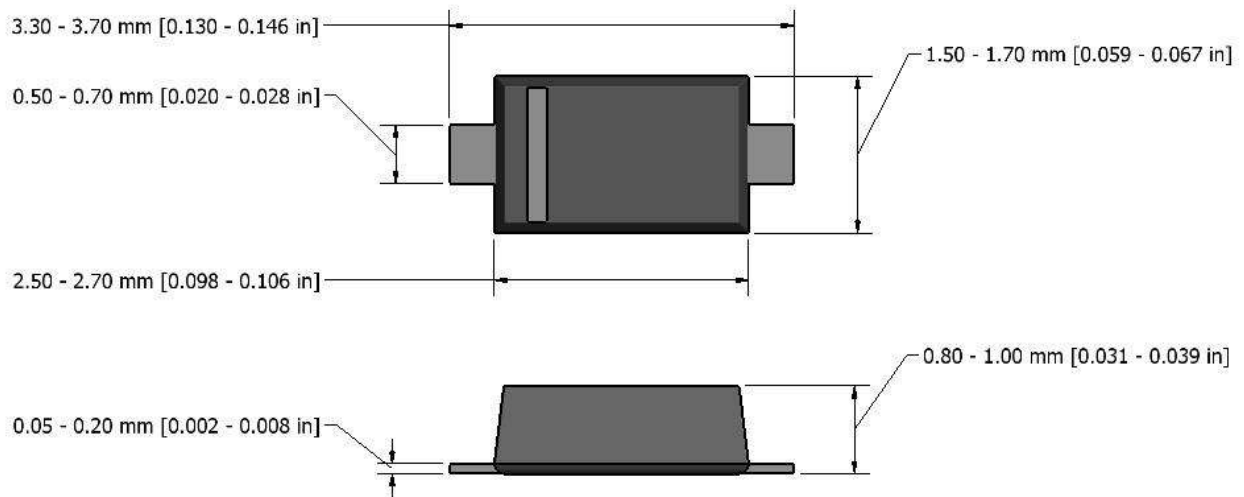
Forward Voltage vs Ambient Temperature



Reverse Current vs Reverse Voltage



Flat Lead SOD-123F Package Outline



Note: Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.

Reel Taping Specifications For Surface Mount Devices-SOD-123F

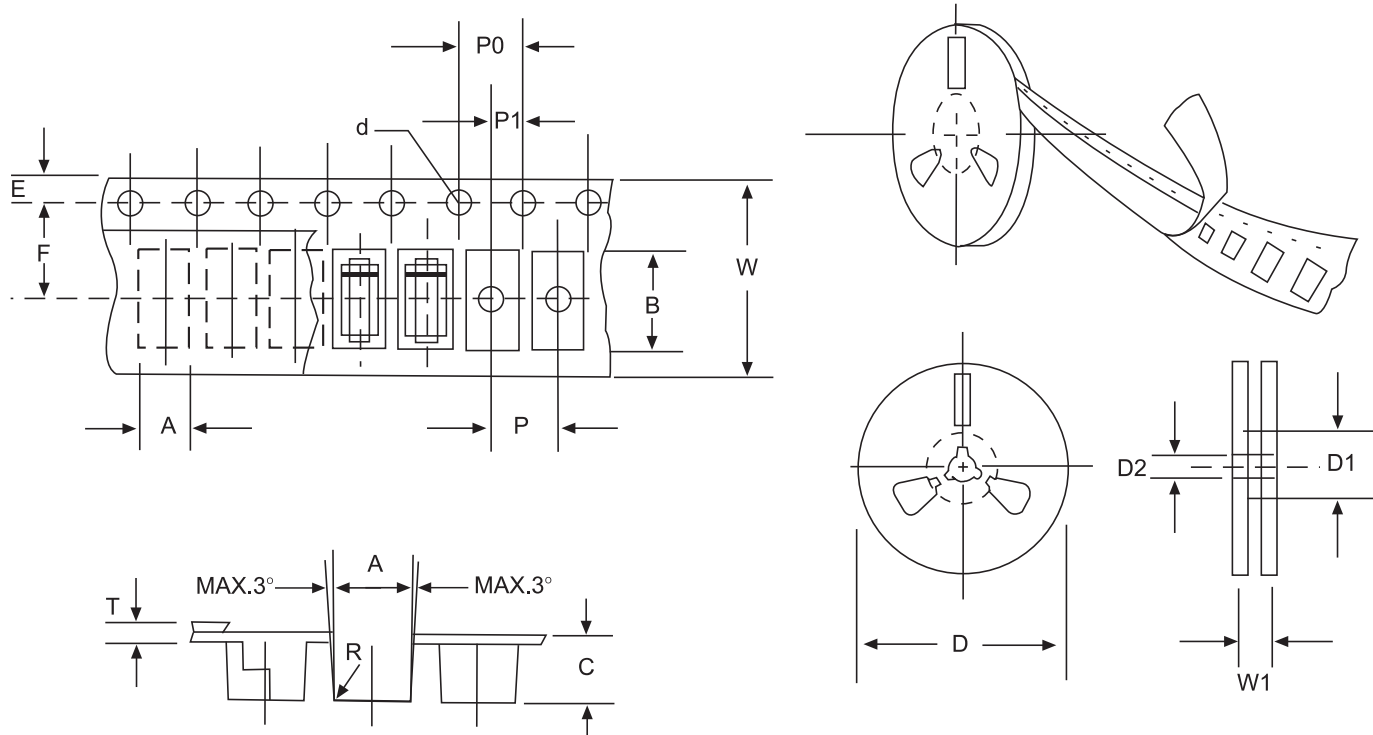


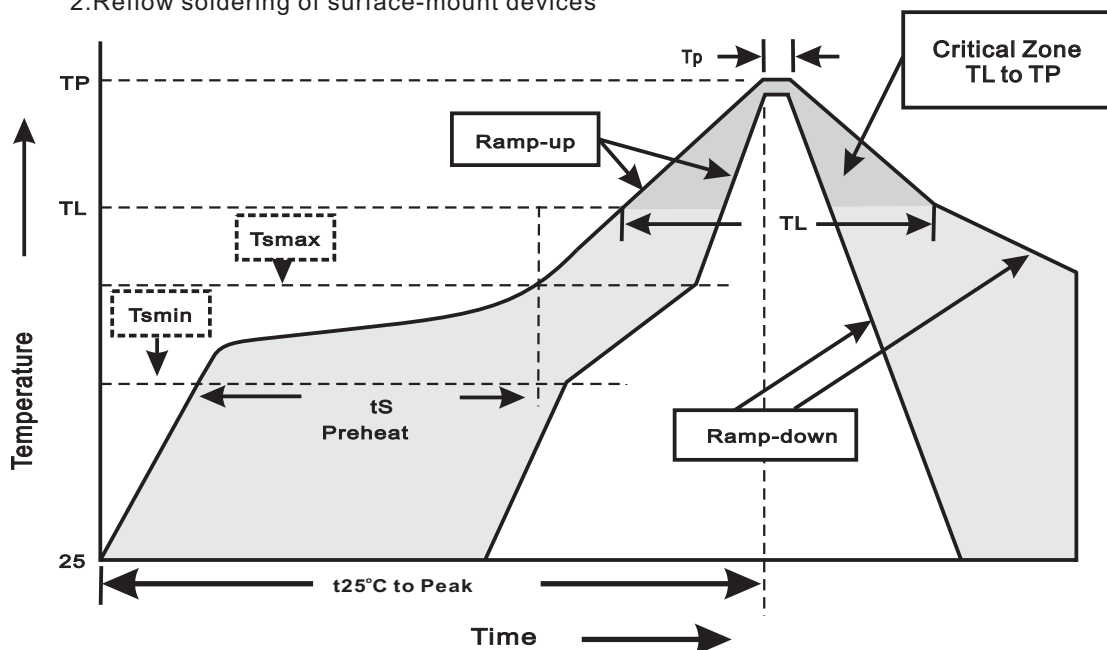
FIG:CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SOD-123F mm(inch)
Carrier width	A	2.05±0.1(0.081±0.004)
Carrier length	B	3.95±0.1(0.156±0.004)
Carrier depth	C	1.45±0.1(0.057±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	178±2.0(7.0±0.079)
Reel inner diameter	D1	54±1.0(2.13±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Sprocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	3.50±0.1(0.138±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Total tape thickness	T	0.21±0.25(0.008±0.010)
Tape width	W	8.0±0.2(0.315±0.008)
Reel width	W1	10.0±2.0(0.394±0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smin}) -Temperature Max(T _{smax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes